

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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3mm One Position SMD CBI Housing

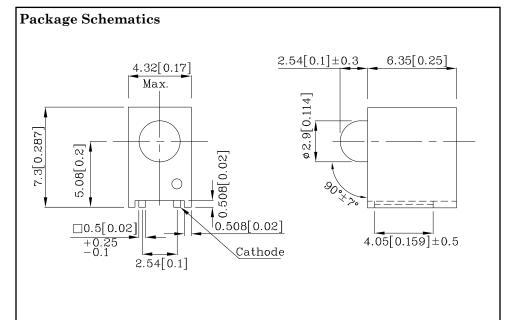
Features

- Black casing provides superior contrast
- Reliable & robust
- Standard Package: 500pcs/ Reel
- MSL (Moisture Sensitivity Level): 3
- Housing UL rating:94V-0.
- Housing material: PPA
- High temperature resistant housing.
- High glass transition temperature epoxy.
- RoHS compliant.

Oct 10,2016







Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		Red (GaAsP/GaP)	Unit
Reverse Voltage	V_{R}	5	V
Forward Current	I_{F}	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i_{FS}	160	mA
Power Dissipation	P_{D}	75	mW
Operating Temperature	T_{A}	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

Operating Characteristics (T_A =25°C)		Red (GaAsP/GaP)	Unit
Forward Voltage (Typ.) $(I_F=10\text{mA})$	V_{F}	1.9	V
Forward Voltage (Max.) $(I_F=10mA)$	V_{F}	2.5	V
Reverse Current (Max.) $(V_R=5V)$	I_R	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) $(I_F=10\text{mA})$	λР	627*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) $(I_F=10\text{mA})$	λD	617*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	Δλ	45	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	15	pF

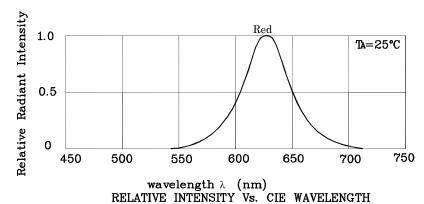
Part Number	Emitting Color	Emitting Material	Lens-color	$\begin{array}{c} \text{Luminous Intensity} \\ \text{CIE127-2007*} \\ \text{(I}_{\text{F}}\text{=}10\text{mA}) \\ \text{mcd} \end{array}$		Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min.	typ.		
XNK1LUR11DSMD	Red	GaAsP/GaP	Red Diffused	12 10*	29 19*	627*	50°

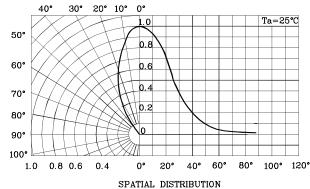
^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.



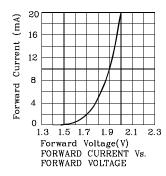


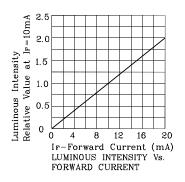
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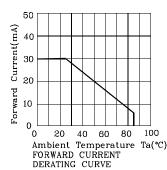


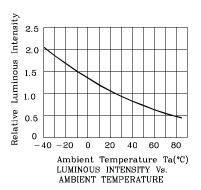


❖ Red

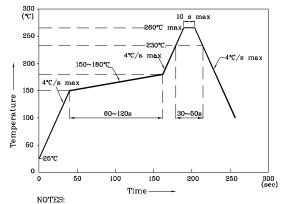








Reflow Soldering Profile for SMD Products (Pb-Free Components)



- 1. We recommend the reflow temperature $245^{\circ}\text{C}(+/-5^{\circ}\text{C})$. The maximum soldering temperature should be limited to 260°C.
- 2. Don't cause stress to the epoxy resin while it is exposed to high temperature

3. No more than once.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

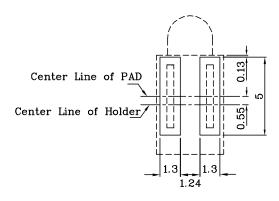
- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

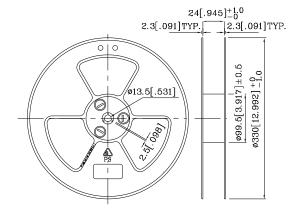
3mm One Position SMD CBI Housing



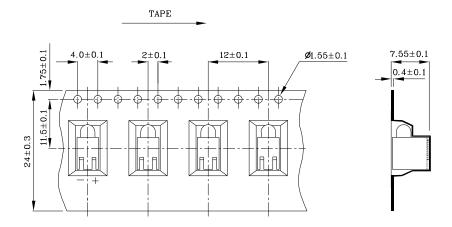
* Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



* Reel Dimension



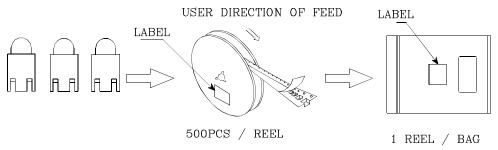
* Tape Specification (Units:mm)

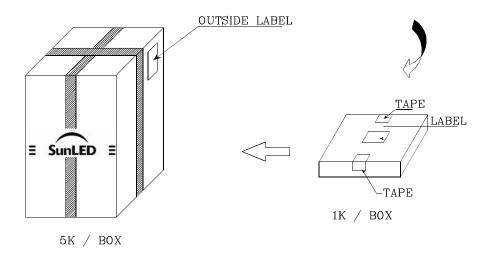


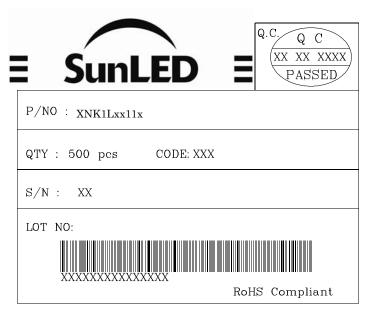


3mm One Position SMD CBI Housing

PACKING & LABEL SPECIFICATIONS







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- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet. User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
- 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
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- 6. Additional technical notes are available at http://www.SunLEDusa.com/TechnicalNotes.asp

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